

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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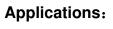


GHIS025A120T1P2 Si IGBT/ SiC SBD PIM Module

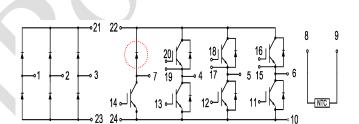


Features:

- Short Circuit Rated 10µs
- Low Saturation Voltage: $V_{CE (sat)} = 1.90V @ I_C = 25A$, $T_C=25^{\circ}C$
- Low Switching Loss
- SiC SBD for boost diode: V_F = 1.50V @ I_F = 15A , T_C =25°C
- 100% RBSOA Tested (2×Ic)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement



- Industrial Inverters
- Servo Applications



IGBT, Inverter Maximum Rated Values (T_C=25°C unless otherwise specified)

V _{CES}	Collector-Emitter Blocking Voltage		1200	V
V _{GES}	Gate-Emitter Voltage		±20	V
	I _C Continuous Collector Current	T _C = 80°C	25	Α
I _C Continuous Collector Current	Continuous Collector Current	T _C = 25°C	50	Α
I _{CM(1)}	Repetitive Peak Collector Current	T _J = 175℃	50	Α
t _{sc}	Short Circuit Withstand Time		>10	μs
P _D	Maximum Power Dissipation per IGBT	T _C = 25℃ T _{Jmax} =175℃	260	W

Page 1 of 12 Rev. 0.1 4/22/2015



Electrical Characteristics of IGBT (T_C =25 $^{\circ}$ C unless otherwise specified)

Static characteristics

Symbol	Description	Conditions		Min	Тур	Max	Unit
$V_{\text{GE(th)}}$	Gate-Emitter Threshold Voltage	I_C = 1 mA, V_{CE} = V_{GE}		5.0	5.5	6.0	V
.,	Callage of a Frankley Seek making Valley as	Emitter Saturation Voltage	T _J = 25℃		1.90	2.20	V
V _{CE(sat)}	Collector-Emiller Saturation Voltage		T _J = 125℃		2.20		V
I _{CES}	Collector-Emitter Leakage Current	V _{GE} = 0V, V _{CE} = V _{CES} , T _J = 25℃)1	mA
I _{GES}	Gate-Emitter Leakage Current	$V_{GE} = \pm 20V$, $V_{CE} = 0V$, $T_{J} = 0$				100	nA
C _{ies}	Input Capacitance	V_{CE} = 25V, V_{GE} = 0V , f = 1MHz		7	3.40		nF
C _{res}	Output capacitance			1	0.13		nF

Switching Characteristics

	0.14.40.0.104.00					
+	Turn on Dolov Timo		T _J = 25℃		140	20
t _{d(on)}	Turn-on Delay Time		T _J = 125℃		140	ns
1	Dies Time		T _J = 25℃		45	
t _r	Rise Time		T _J = 125℃		50	ns
4	Turn off Dolov Time		T _J = 25℃		165	
t _{d(off)}	Turn-off Delay Time	$V_{CC} = 600V, I_C = 25A,$	T _J = 125℃		170	ns
4	Fall Time $V_{CC} = 000V_{,IC} = 25A_{,}$ $R_{G} = 15\Omega_{,}V_{GE} = \pm 15V_{,}$ Inductive Load	T _J = 25℃		220	no	
t _f	f Fall Tillle	inductive Load	T _J = 125℃		330	ns
_	Turn on Switching Long	TJ	T _J = 25℃		1.76	mJ
E _{on}	Turn-on Switching Loss		T _J = 125℃		2.13	IIIJ
_	Turn off Cuitabing Logo		T _J = 25℃		1.02	m l
E _{off}	Turn-off Switching Loss		T _J = 125℃		1.72	mJ
Q_g	Total Gate Charge		T _J = 25℃		120	nC
RBSOA	Reverse Bias Safe Operation Area	I_C =50A, V_{CC} =960V, V_P =1200V, Rg = 15 Ω , V_{GE} =+15V to 0V, T_J =150°C		,	Trapezoid	
SCSOA	Short Circuit Safe Operation Area	V_{CC} = 600V, V_{GE} = 15V, T_{J} = 150°C		10		μs
R _{0JC}	IGBT Thermal Resistance: June	ction-To-Case			0.57	°C/W

Page 2 of 12 Rev. 0.1 4/22/2015



Diode, Inverter Maximum Rated Values ($T_C=25^{\circ}C$ unless otherwise specified)

V _{RRM}	Repetitive Peak Reverse Voltage	1200	V
I _F	Diode Continuous Forward Current	25	Α
I _{FM}	Repetitive Peak Forward Current	50	Α

Electrical Characteristics of FWD (T_C =25 $^{\circ}$ C unless otherwise specified)

Symbol	Description	Condition	ns	Min	Тур	Max	Unit
V _{FM}	Forward Voltage	I _F = 25A ,	T _J = 25℃	1	1.80	2.30	V
VFM	Polward Voltage	V _{GE} = 0V	T _J = 125℃	7	2.00		V
	Peak Reverse Recovery Current		T _J = 25℃		15		Α
Im	reak Reverse Recovery Guiterit		T _J = 125℃		20		τ.
Q _{rr}	Reverse Recovery Charge	I _F =25A, di/dt =580A/μs,	T _J = 25℃		1.05		μC
Q _{rr}	Reverse Recovery Charge	$V_{rr} = 600V, V_{GE} = -15V$	T _J = 125℃		2.19		μ
E _{rec}	Reverse Recovery Energy		T _J = 25℃		0.39		mJ
∟rec	Reverse Recovery Ellergy		T _J = 125℃		0.95		1113
R _{θJC}	Diode Thermal Resistance: Junction-To-Case				0.80		°C/W

IGBT, Brake-Chopper Maximum Rated Values (T_C =25 $^{\circ}$ C unless otherwise specified)

V _{CES}	Collector-Emitter Blocking Voltage		1200	V
V _{GES}	Gate-Emitter Voltage		±20	V
	Continuous Callactor Current	T _C = 80°C	15	Α
Ic	Continuous Collector Current	T _C = 25°C	30	Α
I _{CM}	Peak Collector Current Repetitive	T _J = 175℃	30	Α
t _{sc}	Short Circuit Withstand Time		>10	μs
P _D	Maximum Power Dissipation (IGBT)	T _C = 25 °C T _{Jmax} =175 °C	205	W

Page 3 of 12 Rev. 0.1 4/22/2015



Electrical Characteristics of IGBT (T_C =25 $^{\circ}$ C unless otherwise specified)

Static characteristics

Symbol	Description	Conditions		Min	Тур	Max	Unit
$V_{\text{GE(th)}}$	Gate-Emitter Threshold Voltage	I_C = 1 mA, V_{CE}	I _C = 1 mA, V _{CE} = V _{GE}		5.5	6.5	V
V	Calle stor. Excittor Catringtion Valteria	I _C = 15 A,	T _J = 25℃		1.90	2.10	V
V _{CE(sat)}	Collector-Emitter Saturation Voltage		T _J = 125℃		2.20	AC	V
I _{CES}	Collector-Emitter Leakage Current	V _{GE} = 0V, V _{CE} = V _{CES} , T _J = 25°C				1	mA
I _{GES}	Gate-Emitter Leakage Current	$V_{GE} = \pm 20V$, $V_{CE} = 0V$, $T_{J} = 0$			K	100	nA
C _{ies}	Input Capacitance	V_{CE} = 25V, V_{GE} = 0V , f = 1MHz			2.0		nF
Coes	Output Capacitance				0.10		nF

Switching Characteristics

Qg	Total Gate Charge Reverse Bias Safe Operation	I _C =30A,V _{CC} =960V,Vp=120	T _J = 25℃	140	nC
E _{off}	Turn-off Switching Loss		T _J = 25°C T _J = 125°C	0.63 1.09	mJ
E _{on}	Turn-on Switching Loss		T _J = 25℃ T _J = 125℃	1.74 2.08	mJ
t _f	Fall Time	V _{CC} = 600V,I _C = 15A,	T _J = 25℃ T _J = 125℃	380	ns
$t_{\text{d(off)}}$	Turn-off Delay Time		T _J = 25°C T _J = 125°C	140	ns
t _r	Rise Time		T _J = 25°C T _J = 125°C	50 55	ns
$t_{\text{d(on)}}$	Turn-on Delay Time		T _J = 25°C T _J = 125°C	175 160	ns

Page 4 of 12 Rev. 0.1 4/22/2015



Maximum Rated Values of SiC SBD Brake-Chopper (T_C=25°C unless otherwise specified)

Symbol	Description	Conditions	Value	Unit
V _{RRM}	Repetitive Peak Reverse Voltage	T _j =25 °C	1200	V
I _F	Diode Continuous Forward Current	T _C =125 °C, T _j =175 °C	15	Α
I _{F,SM}	Surge Non-repetitive Forward Current	T_C =125 °C, t_p =8.3 ms sine half wave	75	Α
dv/dt	Diode dv/dt Ruggedness	Turn-on slew rate, repetitive	50	V/ns

Electrical Characteristics of SiC SBD (T_C=25°C unless otherwise specified)

Symbol	Description	Conditions		Min	Тур	Max	Unit	
V _R	DC Blocking Voltage	I _R =100 uA	I _R =100 uA				V	
V	Forward Voltage	I _F = 15A,	T _J = 25℃		1.5	1.7	V	
V _F	V _{GE} = UV T _J	T _J = 175℃	7	2.3		V		
	Deverse leakage Current	e leakage Current	T _J = 25℃		4.1	100		
I _R	Reverse leakage Current	V _R =1200V	T _J = 175℃		606		μΑ	
Q _C	Total Capacitive Charge	V _R =1200V	T _J = 25℃		52		nC	
		V _R =1V, f=1 MHz			895			
С	Total Capacitance	V _R =600V, f=1 MHz			52		pF	
		V _R =1200V, f=1 MHz	2		43		-	
R _{0JC}	Diode Thermal Resistance: Junction-To-Case				TBD		°C/W	

Electrical Characteristics of FWD (T_C=25 °C unless otherwise specified)

Symbol	Description	Conditio	ns	Min	Тур	Max	Unit
V	Forward Voltage	I _F = 25 A ,	T _J = 25℃		1.80	2.30	V
V _{FM}	Folward Voltage	V _{GE} = 0V	T _J = 125℃		2.00		V
	Dook Poverse Pecevery Current		T _J = 25℃		15		А
ı ^m	Peak Reverse Recovery Current		T _J = 125℃		20		A
0	di/dt = 50	I _F =25A, di/dt =580A/μs,	T _J = 25℃		1.05		
Q _{rr}	Reverse Recovery Charge	$V_{rr} = 600V,$ $V_{GE} = -15V$	T _J = 125℃		2.19		μC
_	Dovorno Dopovoru Energy		T _J = 25℃		0.39		ml
E _{rec} R	Reverse Recovery Energy		T _J = 125℃		0.95		- mJ
R _{0JC}	Diode Thermal Resistance: Junction-To-Case				0.80		°C/W

Page 5 of 12 Rev. 0.1 4/22/2015



Diode, Rectifier Maximum Rated Values ($T_C=25^{\circ}C$ unless otherwise specified)

V _{RRM}	Repetitive Peak Reverse Voltage	T _J =25℃	1800	V
I _{FRMSM}	Maximum RMS Forward Current per Chip	T _J =80℃	35	Α
I _{RMSM}	Maximum RMS Current at Rectifier Output	T _J =80℃	45	Α
	Current Ott 10 mag	T _J =25℃	280	٨
I _{FSM}	Surge Current @t _p =10 ms	T _J =150℃	250	Α
124	124 value	T _J =25℃	500	A ² s
l ² t	l²t - value	T _J =150℃	370	A ⁻ S

Electrical Characteristics of Diode (T_C=25°C unless otherwise specified)

Symbol	Description	Conditions		Min	Тур	Max	Unit
V _F	Forward voltage	I _F = 25 A	T _J =25℃		1.05		V
			T _J =150℃		1.00		
I _R	Reverse current	V _R =1200V	T _J =25℃			1	mA
R _{θJC}	Junction-To-Case Diode	170			0.89		°C/W

Internal NTC-Thermistor Characteristics

Symbol	Description	Min	Тур	Max	Unit
R ₂₅	T _C =25℃		5		kΩ
△R/R	T _C =100°C,R ₁₀₀ =481Ω			±5	%
P ₂₅	T _C =25℃		50		mW
B _{25/50}	$R_2=R_{25} \exp[B_{25/50}(1/T_2-1/(298.15K))]$		3380		К
B _{25/80}	$R_2=R_{25} \exp[B_{25/80}(1/T_2-1/(298.15K))]$		3440		K

Page 6 of 12 Rev. 0.1 4/22/2015

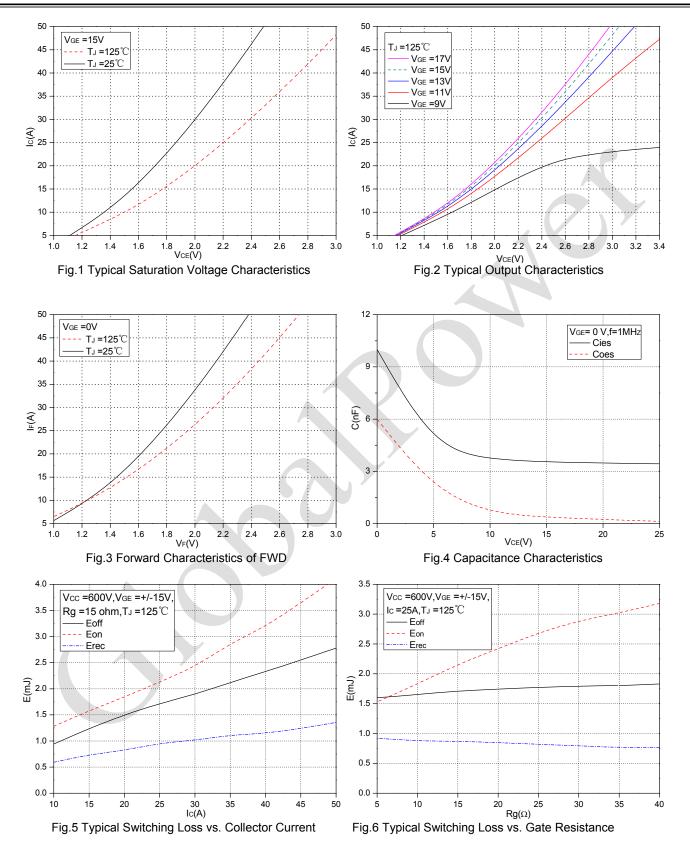


Module

Symbol	Description		Min	Тур	Max	Unit
V _{iso}	Isolation Voltage(All Terminals Shorted)	f = 50Hz, 1minute			2500	V
TJ	Maximum Junction Temperature				175	$^{\circ}$
T _{JOP}	Maximum Operating Junction Temperature Range		-40		+150	$^{\circ}$
T _{stg}	Storage Temperature				+125	$^{\circ}$
R _{ecs}	Case-To-Sink (Conductive Grease Applied)			0.1		°C/W
М	Mounting Screw:M5				5.0	N·m
G	Weight		1	200		g

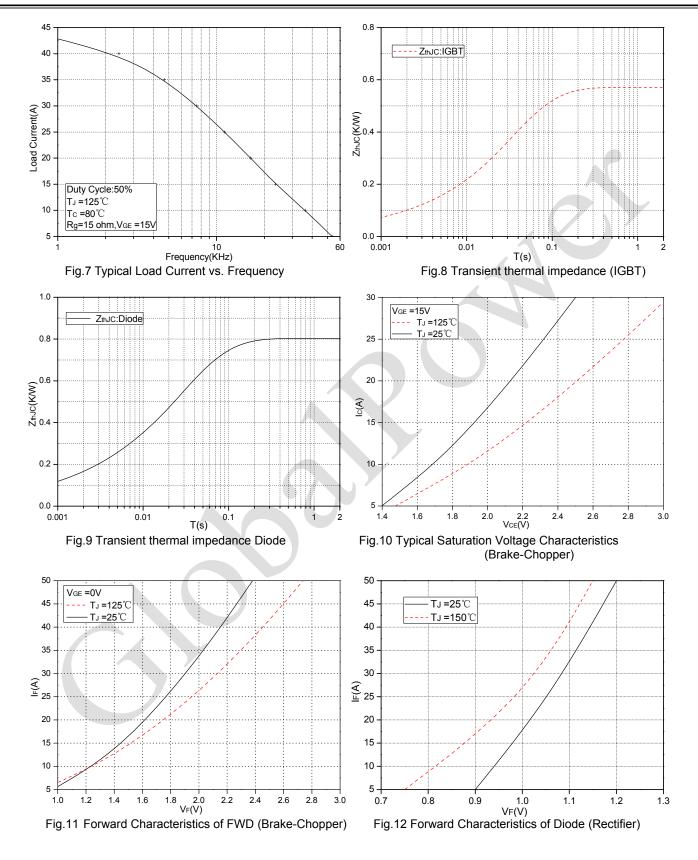
Page 7 of 12 Rev. 0.1 4/22/2015





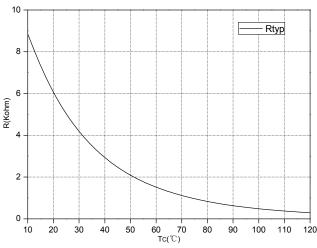
Page 8 of 12 Rev. 0.1 4/22/2015





Page 9 of 12 Rev. 0.1 4/22/2015





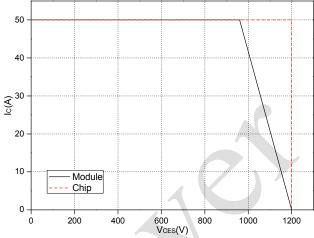
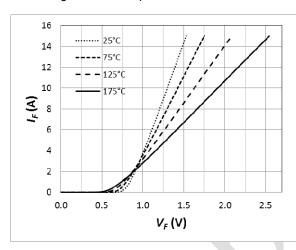


Fig.13 NTC Temperature characteristics

Fig.14 Reverse Bias Safe Operation Area (RBSOA)



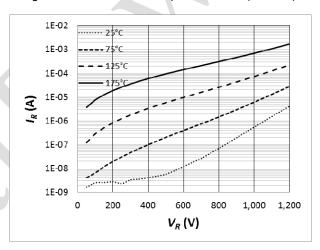
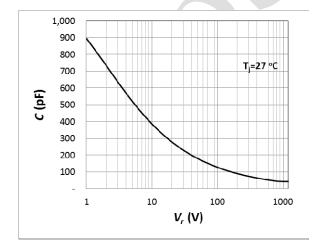


Fig. 15 Forward Characteristics of SiC Diode (Boost)

Fig. 16 Leakage Current of SiC Diode (Boost)



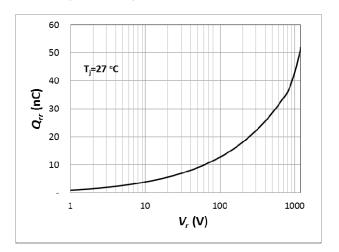
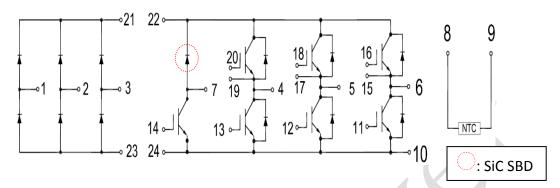


Fig. 17 Capacitance Characteristics of SiC Diode (Boost)

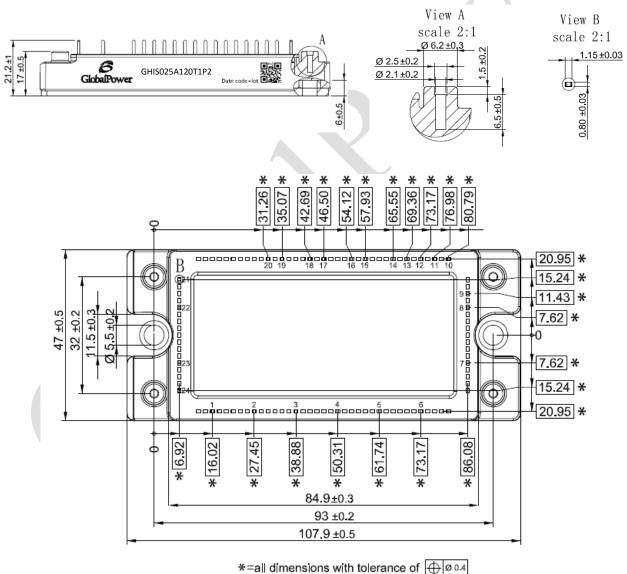
Fig. 18 Recovery Charge of Boost SiC Diode (Boost)

Page 10 of 12 Rev. 0.1 4/22/2015

Internal Circuit:



Package Outline (Unit: mm):



Page 11 of 12 Rev. 0.1 4/22/2015



Revision History

Date	Revision	Notes	
4/22/2015	0.1	Initial release of preliminary datasheet	

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Notes

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented March, 2013. RoHS Declarations for this product can be obtained from the Product Documentation sections of www.gptechgroup.com.

REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact our office at GPTG Headquarters in Lake Forest, California to insure you get the most up-to-date REACh SVHC Declaration.

REACh banned substance information (REACh Article 67) is also available upon request.

- This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, or air traffic control.
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Page 12 of 12 Rev. 0.1 4/22/2015